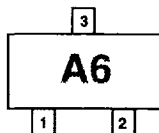
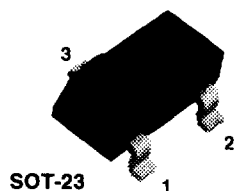
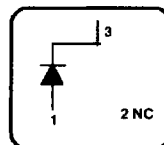


BAS16


CONNECTION DIAGRAM


High Conductance Ultra Fast Diode

Sourced from Process 1P. See BAV99 for characteristics.

Absolute Maximum Ratings*

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
W_{IV}	Working Inverse Voltage	75	V
I_O	Average Rectified Current	200	mA
I_F	DC Forward Current	600	mA
i_F	Recurrent Peak Forward Current	700	mA
$i_F(\text{surge})$	Peak Forward Surge Current Pulse width = 1.0 second Pulse width = 1.0 microsecond	1.0 2.0	A A
T_{stg}	Storage Temperature Range	-50 to +150	°C
T_J	Operating Junction Temperature	150	°C

*These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

NOTES:

- 1) These ratings are based on a maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

TA = 25°C unless otherwise noted

Symbol	Characteristic	Max	Units
		BAS16	
P_D	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

High Conductance Ultra Fast Diode
(continued)

Electrical Characteristics

T_A = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
B _V	Breakdown Voltage	I _R = 5.0 μA	85		V
I _R	Reverse Current	V _R = 25 V, T _A = 150°C V _R = 75 V V _R = 75 V, T _A = 150°C		30 1.0 50	μA μA μA
V _F	Forward Voltage	I _F = 1.0 mA I _F = 10 mA I _F = 50 mA I _F = 150 mA		715 855 1.0 1.25	mV mV V V
C _O	Diode Capacitance	V _R = 0, f = 1.0 MHz		2.0	pF
T _{RR}	Reverse Recovery Time	I _F = 10 mA, V _R = 6.0 V, I _{RR} = 1.0 mA, R _L = 100Ω		6.0	nS